



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





## **SMT power inductors**

Size 12.95 × 9.4 × 5.08 (mm)

**Series/Type:**            **B82476A1**

**Date:**                    **June 2012**

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**SMD**
**Rated inductance 1 ... 1000  $\mu$ H**
**Rated current 0.3 ... 6.8 A**
**Construction**

- Ferrite core
- Winding: enamel copper wire
- Winding soldered to terminals
- Plastic terminal carrier


**Features**

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

**Applications**

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics
- Consumer electronics

**Terminals**

- Base material CuSn6P
- Schichtaufbau Ni, Sn (lead-free)
- Electro-plated

**Marking**

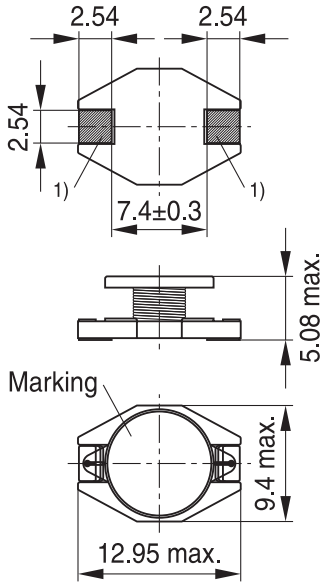
- Marking on component:  
Manufacturer, L value ( $\mu$ H, coded),  
manufacturing date (YWWD)
- Minimum marking on reel:  
Manufacturer, ordering code, L value,  
quantity, date of packing

**Delivery mode and packing unit**

- 24-mm blister tape, wound on 330-mm  $\varnothing$  reel
- Packing unit: 750 pcs./reel

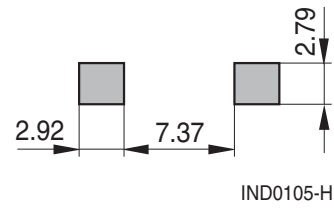
**SMD**

**Dimensional drawing and layout recommendation**



1) Soldering area

IND0489-B-E



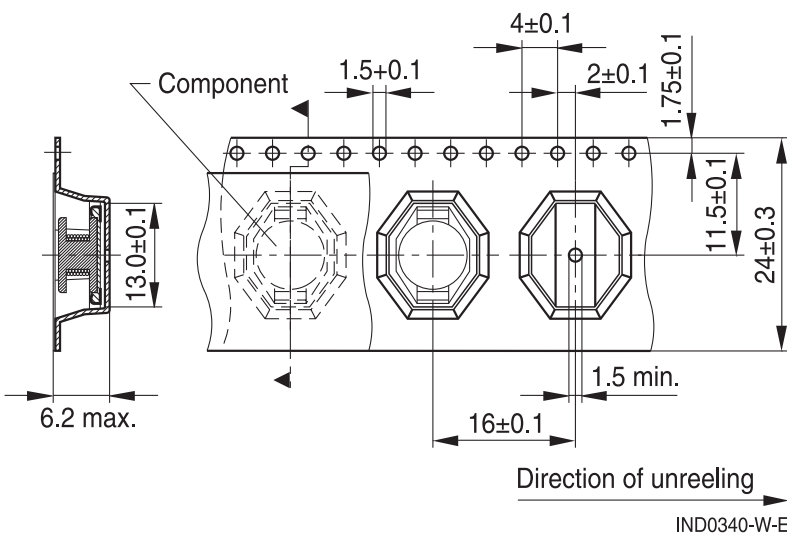
IND0105-H

Dimensions in mm

Component tolerances ±0.2 mm unless otherwise noted.

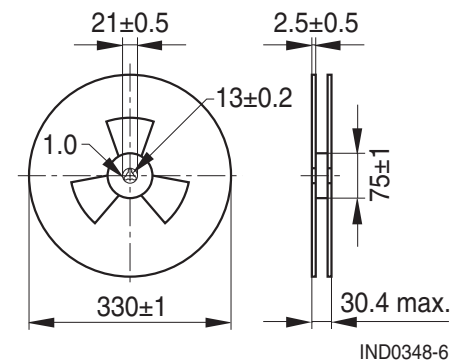
**Taping and packing**

**Blister tape**



IND0340-W-E

**Reel**



IND0348-6

Dimensions in mm



**SMD**
**Technical data and measuring conditions**

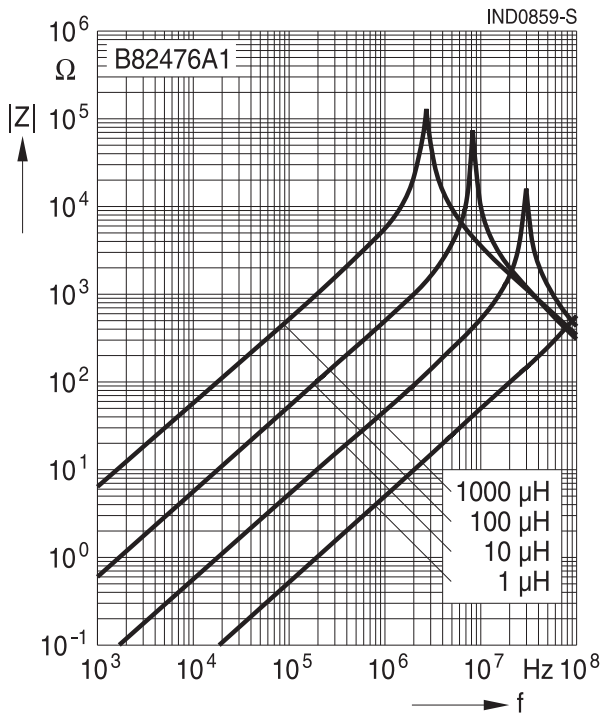
Rated inductance $L_R$	Measured with LCR meter Agilent 4284A at frequency $f_L$ , 0.1 V, +20 °C
Rated temperature $T_R$	+85 °C
Rated current $I_R$	Max. permissible DC with temperature increase of $\leq 40$ K at rated temperature
Saturation current $I_{sat}$	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance $R_{max}$	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 1.3 g

**Characteristics and ordering codes**

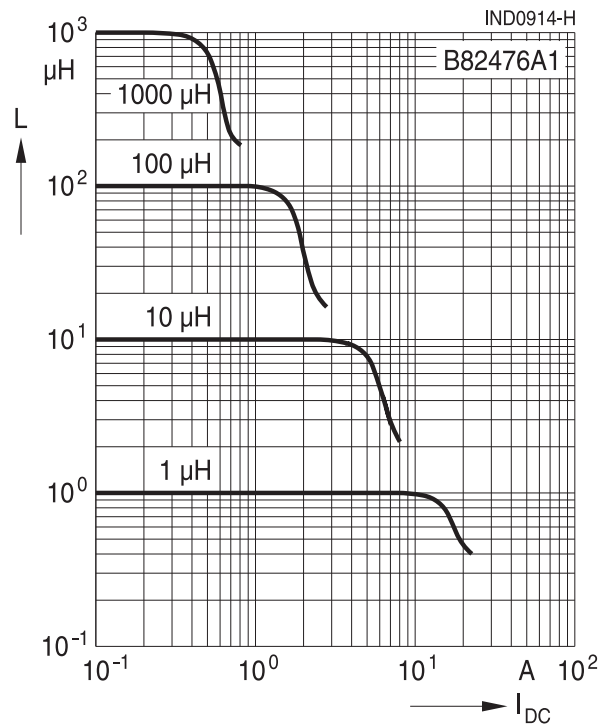
$L_R$ $\mu\text{H}$	Tolerance	$f_L$ MHz	$I_R$ A	$I_{sat}$ A	$R_{max}$ $\Omega$	Ordering code
1.0	$\pm 20\% \triangleq M$	0.1	6.8	9.0	0.0080	B82476A1102M000
1.5		0.1	6.4	8.0	0.0090	B82476A1152M000
2.2		0.1	6.1	7.0	0.0105	B82476A1222M000
3.3		0.1	5.4	6.4	0.0135	B82476A1332M000
4.7		0.1	4.8	5.4	0.0165	B82476A1472M000
6.8		0.1	4.4	4.6	0.0210	B82476A1682M000
10		0.1	3.9	3.8	0.0270	B82476A1103M000
15		0.1	3.1	3.0	0.0400	B82476A1153M000
22		0.1	2.7	2.6	0.0500	B82476A1223M000
33		0.1	2.1	2.0	0.0880	B82476A1333M000
47		0.1	1.8	1.6	0.120	B82476A1473M000
68		0.1	1.5	1.4	0.160	B82476A1683M000
100		0.1	1.3	1.2	0.230	B82476A1104M000
150		0.1	1.0	1.0	0.330	B82476A1154M000
220		0.1	0.8	0.8	0.530	B82476A1224M000
330		0.1	0.6	0.6	0.810	B82476A1334M000
470	0.1	0.5	0.5	1.10	B82476A1474M000	
680	0.1	0.4	0.4	1.60	B82476A1684M000	
1000	0.1	0.3	0.3	2.15	B82476A1105M000	

**SMD**

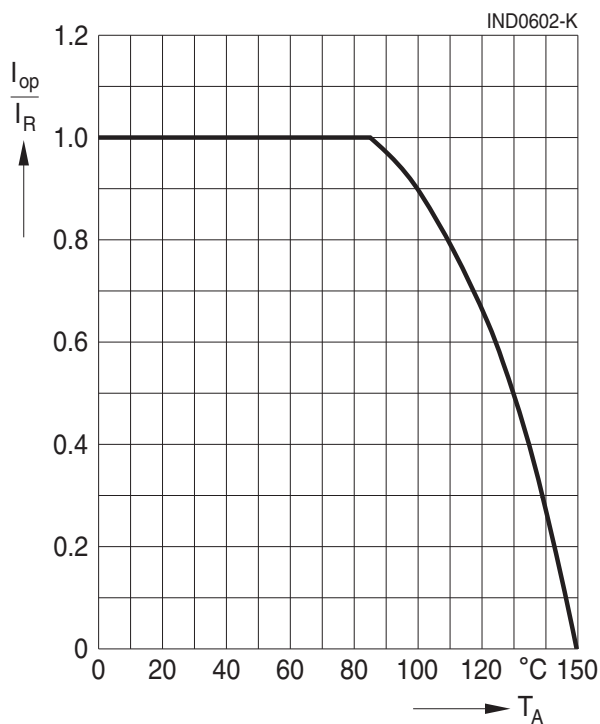
**Impedance  $|Z|$  versus frequency  $f$**   
measured with impedance analyzer  
Agilent 4294A, typical values at +20 °C



**Inductance  $L$  versus DC load current  $I_{DC}$**   
measured with LCR meter Agilent 4275A,  
typical values at +20 °C



**Current derating  $I_{op}/I_R$**   
**versus ambient temperature  $T_A$**   
(rated temperature  $T_R = +85$  °C)



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

## Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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